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Fundamentals of Microsystems Packaging. by: Rao R. Tummala. Abstract: A rigorous and thorough introduction to electronic packaging technologies. Each chapter covers a single major packaging technology illustrated with schematics and diagrams. Aspects of electrical, mechanical, chemical, and materials packaging are identified in each chapter.

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The course provides hands-on instruction in electronics packaging, including assembly, reliability, thermal management, and test of next-generation microsystems. Textbook: Rao R. Tummala, Madhavan Swaminathan, Introduction to System-on-Package (SOP), McGraw-Hill, 2008. Rao R. Tummala, Fundamentals of Microsystems Packaging, McGraw-Hill, 2001.

ECE/ME 4754 Electronics Packaging Assembly (Elective)

"Fundamentals of Microsystems Packaging" is an informative, well-written textbook, the first to cover this rapidly-evolving technology. Professor Tummala's latest book should appeal to only three groups: those who know a lot about microsystems packaging, those who know something about it, and those who know nothing about it.

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